

Customer No.: 31561
Application No.: 10/711,675
Docket NO.: 13434-US-PA

In The Claims:

Claim 1. (currently amended) An electronic package with a passive component comprising:

a circuit carrier having a patterning circuit layer and a solder-mask layer formed over said patterning circuit layer, said patterning circuit layer having at least a passive-component-pad set, said passive-component-pad set having a first pad and a second pad;

at least a passive component having a first electrode and a second electrode positioned over said first pad and said second pad, respectively; and

an anisotropic conductive layer arranged between said first electrode and said first pad and between said second electrode and said second pad, wherein said solder-mask layer having at least one opening formed on said passive-component-pad set.

Claim 2. (original) The electronic package of claim 1, wherein said anisotropic conductive layer covers said circuit carrier between said first pad and said second pad.

Claim 3. (original) The electronic package of claim 1, wherein said anisotropic conductive layer covers said first pad and said second pad.

Claim 4. (currently amended) The electronic package of claim 1, wherein said

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~~circuit carrier further includes a solder-mask layer having at least one opening exposing~~
all of the upper surface of said first pad and all of the upper surface of said second pad.

Claim 5. (original) The electronic package of claim 4, wherein there is no solder-mask layer formed between said first pad and said second pad.

Claim 6. (currently amended) The electronic package of claim 1, wherein said ~~circuit carrier further includes a solder-mask layer having at least one opening exposing~~
part of the upper surface of said first pad and part of the upper surface of said second pad.

Claim 7. (original) The electronic package of claim 1, further comprising a molding compound encapsulating said passive component.

Claim 8. (original) The electronic package of claim 1, wherein said passive component comprises a resistor, an inductor or a capacitor.

Claim 9. (original) The electronic package of claim 1, wherein said anisotropic conductive layer is made of anisotropic conductive film (ACF) or anisotropic conductive paste (ACP).

Claim 10. (original) The electronic package of claim 1, further comprising at least a chip electrically connected to said circuit carrier.

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Claim 11. (original) The electronic package of claim 10, wherein said chip is electrically connected to said circuit carrier using a wire-bonding technology or using a flip-chip bonding technology.

Claim 12. (original) The electronic package of claim 1, further comprising multiple electrical contacts arranged on said circuit carrier.

Claim 13. (original) The electronic package of claim 12, wherein said electrical contacts comprise pins or solder balls.

Claim 14. (current amended) An electronic package with a passive component comprising:

a circuit carrier having at least a passive-component-pad set and a solder-mask layer, said passive-component-pad set having multiple pads;

at least a passive component having multiple electrodes positioned over said pads of said circuit carrier, respectively; and

an anisotropic conductive layer arranged between said electrodes and said pads, wherein said solder-mask layer having at least one opening formed on said passive-component-pad set.

Claim 15. (original) The electronic package of claim 14, wherein said

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anisotropic conductive layer covers said circuit carrier between said pads.

Claim 16. (original) The electronic package of claim 14, wherein said anisotropic conductive layer covers said pads.

Claim 17. (currently amended) The electronic package of claim 14, wherein said ~~circuit carrier further includes a solder mask layer having at least one opening~~ exposing all of the upper surface of said pads.

Claim 18. (original) The electronic package of claim 17, wherein there is no solder-mask layer formed among said pads.

Claim 19. (currently amended) The electronic package of claim 14, wherein said circuit carrier ~~further includes a solder mask layer having at least one~~ has a plurality of openings exposing part of the upper surface of said pads, respectively.

Claim 20. (original) The electronic package of claim 14, further comprising a molding compound encapsulating said passive component.

Claim 21. (original) The electronic package of claim 14, wherein said passive component comprises a resistor, an inductor or a capacitor.

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Claim 22. (original) The electronic package of claim 14, wherein said anisotropic conductive layer is made of anisotropic conductive film (ACF) or anisotropic conductive paste (ACP).

Claim 23. (original) The electronic package of claim 14, further comprising at least a chip electrically connected to said circuit carrier.

Claim 24. (original) The electronic package of claim 23, wherein said chip is electrically connected to said circuit carrier using a wire-bonding technology or using a flip-chip bonding technology.

Claim 25. (original) The electronic package of claim 14, further comprising multiple electrical contacts arranged on said circuit carrier.